

# STP5NK100Z, STF5NK100Z STW5NK100Z

## N-channel 1000 V, 2.7 Ω, 3.5 A, TO-220, TO-220FP, TO-247 SuperMESH3™ Power MOSFET

### Features

Туре	V <sub>DSS</sub> (@T <sub>JMAX</sub> )	R <sub>DS(on)</sub> max	I <sub>D</sub>
STF5NK100Z	1000 V	< 3.7 Ω	3.5 A
STP5NK100Z	1000 V	< 3.7 Ω	3.5 A
STW5NK100Z	1000 V	< 3.7 Ω	3.5 A

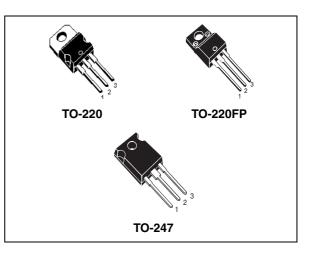
- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatibility

### **Applications**

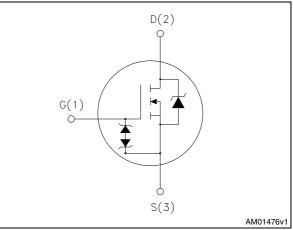
Switching application

## Description

The new SuperMESH<sup>™</sup> series of Power MOSFETS is the result of further design improvements on ST's well-established stripbased PowerMESH<sup>™</sup> layout. In addition to significantly lower on-resistance, the device offers superior dv/dt capability to ensure optimal performance even in the most demanding applications. The SuperMESH<sup>™</sup> devices further complement an already broad range of innovative high voltage MOSFETs, which includes the revolutionary MDmesh<sup>™</sup> products.



### Figure 1. Internal schematic diagram



Order code	Marking	Package	Packaging
STF5NK100Z	F5NK100Z	TO-220FP	Tube
STP5NK100Z	P5NK100Z	TO-220	Tube
STW5NK100Z	W5NK100Z	TO-247	Tube

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## 1 Electrical ratings

Table 2.						
Symbol	Parameter	Val	ue	Unit		
Symbol	Farameter	TO-220, TO-247	TO-220FP			
V <sub>DS</sub>	Drain-source voltage ( $V_{GS} = 0$ )	100	00	V		
V <sub>GS</sub>	Gate-source voltage	± 3	30	V		
Ι <sub>D</sub>	Drain current (continuous) at $T_C = 25^{\circ}C$	3.5	3.5 <sup>(1)</sup>	А		
۱ <sub>D</sub>	Drain current (continuous) at $T_C=100^{\circ}C$	2.2	2.2 <sup>(1)</sup>	А		
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	14	14 <sup>(1)</sup>	Α		
P <sub>TOT</sub>	Total dissipation at $T_{C} = 25^{\circ}C$	125	30	W		
	Derating factor	1	0.24	W/°C		
V <sub>ESD(G-S)</sub>	Gate source ESD (HBM-C=100pF, R=1.5 kΩ)	400	00	v		
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	4.	5	V/ns		
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1 s; Tc= 25°C)		2500	v		
T <sub>J</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	-55 to 150		°C		

Table 2.	Absolute max	kimum ratings

1. Limited only by maximum temperature allowed

2. Pulse width limited by safe operating area

3.  $I_{SD} \leq$  3.5 A, di/dt  $\leq$  200 A/µs,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_j \leq T_{JMAX.}$ 

#### Table 3. Thermal data

Symbol	Parameter	Val	Unit	
Symbol	Farameter	TO-220, TO-247	TO-220FP	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	1 4.2		°C/W
R <sub>thj-a</sub>	Thermal resistance junction-ambient max	62	62.5	
т	Maximum lead temperature for soldering purpose	300		°C

#### Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_{\text{JMAX}}$ )	3.5	А
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>j</sub> =25 °C, Id=Iar, Vdd=50 V)	250	mJ



## 2 Electrical characteristics

(T<sub>CASE</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	1000			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max rating, V <sub>DS</sub> = Max rating, Tc = 125 °C			1 50	μΑ μΑ
I <sub>GSS</sub>	Gate body leakage current (V <sub>GS</sub> = 0)	V <sub>GS</sub> = ± 20 V			±10	μA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \ \mu A$	3	3.75	4.5	V
R <sub>DS(on)</sub>	Static drain-source on resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 1.75 A		2.7	3.7	Ω

#### Table 5. On/off states

#### Table 6. Dynamic

						-
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 1.75 \text{ A}$	-	4		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>DS</sub> =25 V, f=1 MHz, V <sub>GS</sub> =0	-	1154 106 21.3		pF pF pF
C <sub>osseq</sub> <sup>(2)</sup>	Equivalent output capacitance	$V_{GS}$ =0, $V_{DS}$ =0 V to 800 V	-	46.8		pF
t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Turn-on delay time Rise time Off-voltage rise time Fall time	V <sub>DD</sub> =500 V, I <sub>D</sub> = 1.75 A, R <sub>G</sub> =4.7 Ω, V <sub>GS</sub> =10 V (see <i>Figure 21</i> )	-	22.5 7.7 51.5 19		ns ns ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total gate charge Gate-source charge Gate-drain charge	V <sub>DD</sub> =800 V, I <sub>D</sub> = 3.5 A V <sub>GS</sub> =10 V (see <i>Figure 22</i> )	-	42 7.3 21.7	59	nC nC nC

1. Pulsed: pulse duration=300  $\mu$ s, duty cycle 1.5%

2.  $C_{oss\ eq}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ 



	Source drain diode					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		3.5	А
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		14	А
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	I <sub>SD</sub> = 3.5 A, V <sub>GS</sub> =0	-		1.6	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	I <sub>SD</sub> = 3.5 A, di/dt = 100 A/μs, V <sub>DD</sub> =30 V (see <i>Figure 23</i> )	-	605 3.09 10.5		ns μC Α
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	I <sub>SD</sub> = 3.5 A, di/dt = 100 A/μs, V <sub>DD</sub> =35 V, T <sub>j</sub> =150 °C (see <i>Figure 23</i> )	-	742 4.2 11.2		ns μC Α

Table 7.Source drain diode

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration=300  $\mu s,$  duty cycle 1.5%

#### Table 8.Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
BV <sub>GSO</sub>	Gate-source breakdown voltage	lgs=± 1 mA (open drain)	30			V

The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.



### 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220FP Figure 3. Thermal impedance for TO-220FP

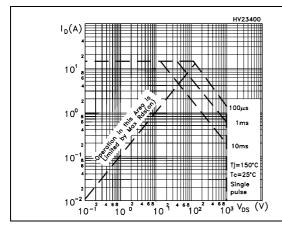


Figure 4. Safe operating area for TO-220

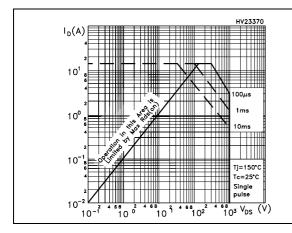


Figure 6. Safe operating area for TO-247

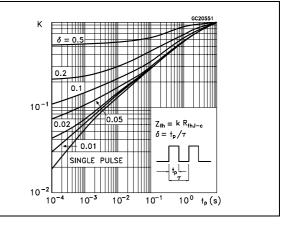


Figure 5. Thermal impedance for TO-220

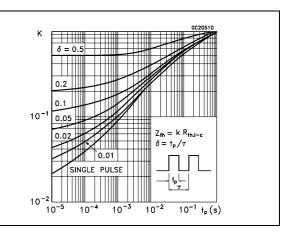
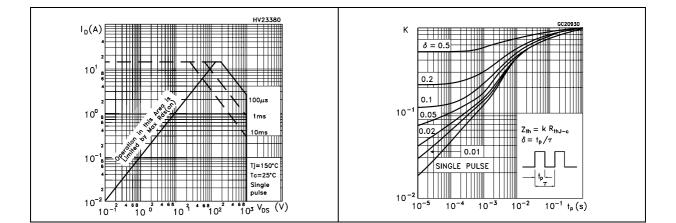
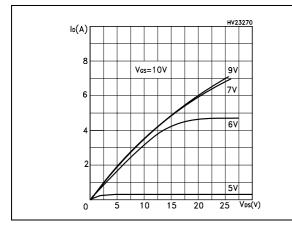


Figure 7. Thermal impedance for TO-247



### Figure 8. Output characteristics



### Figure 10. Transconductance

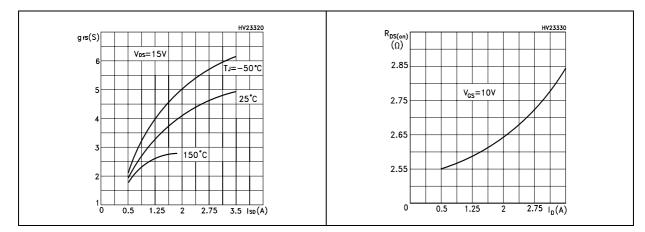
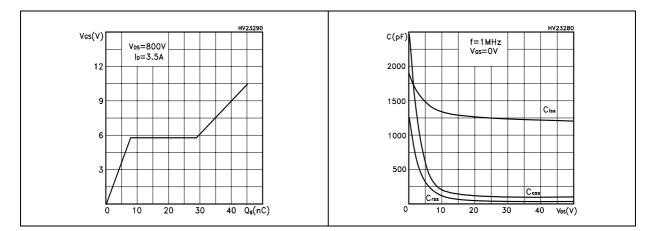


Figure 12. Gate charge vs gate-source voltage Figure 13. Capacitance variations



## Figure 9. Transfer characteristics

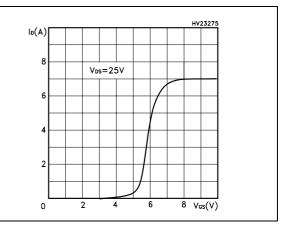


Figure 11. Static drain-source on resistance



#### Figure 14. Normalized gate threshold voltage Figure 15. Normalized on resistance vs vs temperature

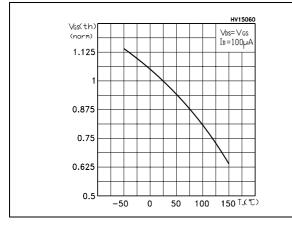


Figure 16. Source-drain diode forward characteristics

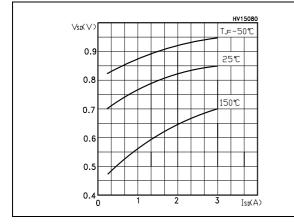
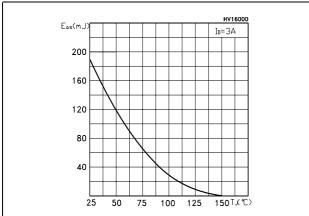


Figure 18. Maximum avalanche energy vs temperature



# temperature

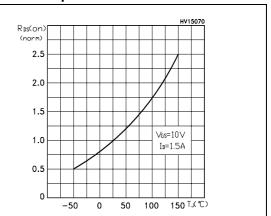
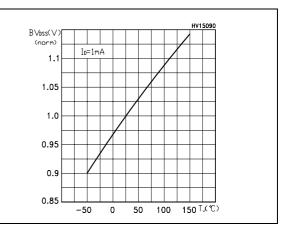


Figure 17. Normalized BVdss vs temperature





## 3 Test circuits

Figure 19. Unclamped inductive load test circuit

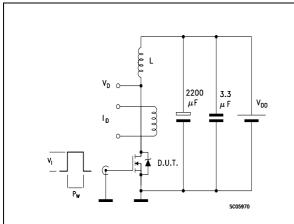
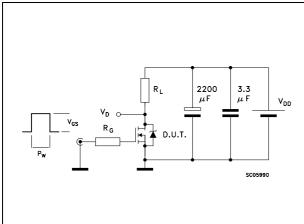
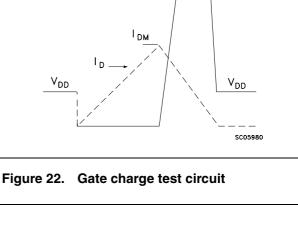


Figure 21. Switching times test circuit for resistive load

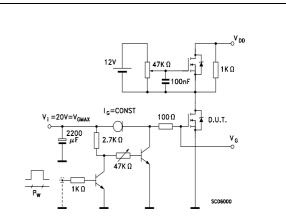




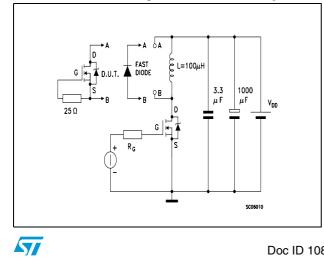
V<sub>(BR)DSS</sub>

## Figure 20. Unclamped inductive waveform

 $\mathsf{V}_\mathsf{D}$ 



# Figure 23. Test circuit for inductive load switching and diode recovery times





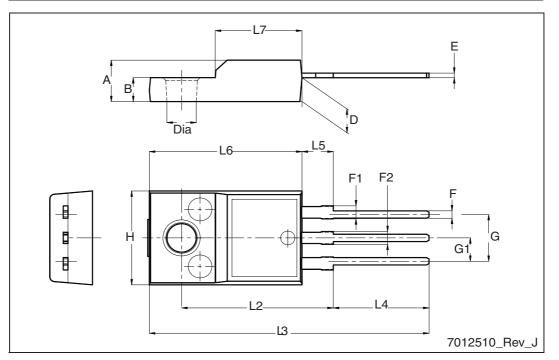
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



TO-220FP	mechanical	data
	moonamoa	MARM

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.4		4.6
В	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.5
G	4.95		5.2
G1	2.4		2.7
Н	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2



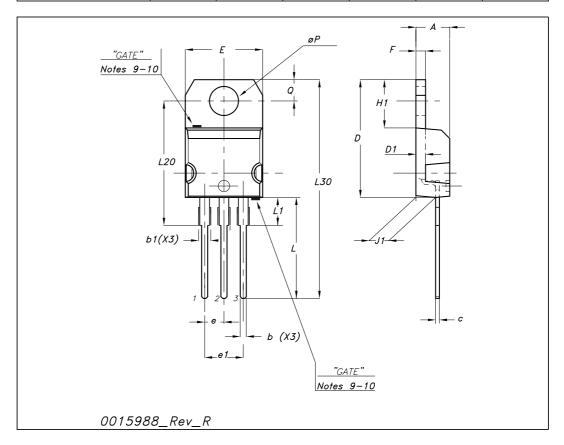


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### Package mechanical data

Dim		mm		inch		
	Min	Тур	Max	Min	Тур	Max
Α	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
С	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
ØP	3.75		3.85	0.147		0.151
Q	2.65	İ	2.95	0.104		0.116

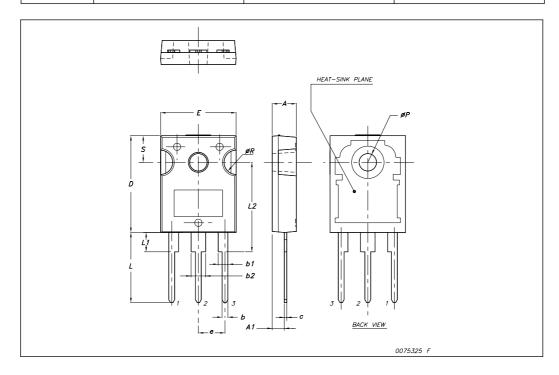




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	TO-247 Mechanical data		
Dim.		mm.	1
	Min.	Тур	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
Е	15.45		15.75
е		5.45	
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
øР	3.55		3.65
øR	4.50		5.50
S		5.50	





## 5 Revision history

Table 9.Document revision history

Date	Revision	Changes
12-Oct-2004	1	First release
08-Sep-2005	2	Complete datasheet
16-Dec-2005	3	Inserted ecopack indication
16-Aug-2006	4	New template, no content change
15-May-2009	5	Modified: Section 2.1: Electrical characteristics (curves)



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